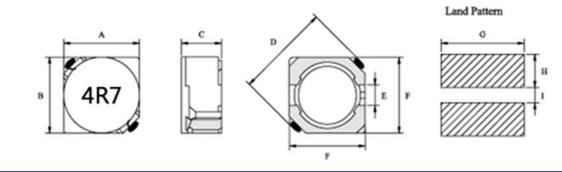


## **FEATRLRES**

- Magnetic Shielded surface mount inductor with high current rating.
- Low resistance to keep power loss minimum.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

## CONFIGRLRATIONS & DIMENSIONS (unit in mm)



Туре	A±0.3	B±0.3	C(max)	D(max)	E(Ref.)	F(Ref.)	G	Н	I
HRH3D16	4.0max	4.0max	1.8	5.2	1.0	4.0max	4.6	1.6	1.4

## **ELECTRICAL CHARACTERISTICS**

Part Number	Inductance (uH)	Tolerance (%)	Test Frequency	DCR	IDC
Part Number			(Hz)	(Ω) max.	(A) max.
HRH3D16-1R5Y	1.5	± 30%	0.1V/100K	0.052	1.55
HRH3D16-2R2Y	2.2	± 30%	0.1V/100K	0.072	1.20
HRH3D16-3R3Y	3.3	± 30%	0.1V/100K	0.085	1.10
HRH3D16-4R7Y	4.7	± 30%	0.1V/100K	0.105	0.90
HRH3D16-6R8Y	6.8	± 30%	0.1V/100K	0.170	0.73
HRH3D16-100Y	10	± 30%	0.1V/100K	0.210	0.55
HRH3D16-150Y	15	± 30%	0.1V/100K	0.295	0.45
HRH3D16-220Y	22	± 30%	0.1V/100K	0.430	0.40
HRH3D16-330Y	33	± 30%	0.1V/100K	0.675	0.32

Note:

Based on inductance change  $(\triangle L/L0 : \le -35\%)$  @ ambient temp. 25°C Based on temperature rise  $(\triangle T : 40$ °C typ.)

## **Reliability and Test Condition**

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	110~+40℃,50~60%RH (Product with taping) 240~+125℃(on board)	



Electrical Performance Test					
Inductance		HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.			
DCR	Refer to standard electrical characteristics list.	CH16502,Agilent33420A Micro-Ohm Meter.			
Saturation Current (Isat)	Approximately \( \triangle L30\)%	Saturation DC Current (Isat) will cause L0 to drop △L(%)			
Heat Rated Current (Irms)	Approximately △T40℃	Heat Rated Current (Irms) will cause the coil temperature rise $\triangle T(^{\circ}C)$ . 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer			
Reliability Test					
Life Test		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature: 125±2°C (Inductor) Applied current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs			
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±2 * R.H, Temperature: 85°C±2°C Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs  Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles  1. Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs. 4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.			
Moisture Resistance	Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value				
Thermal shock		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -40±2°C 30±5min Step2: 25±2°C ≤0.5min Step3: 125±2°C 30±5min Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs			
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations).			
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.			
Shock	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value.	Type			
	RDC : within ±15% of initial value and shall not exceed the specification value	Lead 50 11 Half-sine 11.3			
Solder ability	Preheat: 150°C,60sec.₃  Solder: Sn96.5% Ag3% Cu0.5%  Temperature: 245±5°C ∘  Flux for lead free: Rosin. 9.5% ∘  Dip time: 4±1sec ∘  Depth: completely cover the termination				
Resistance to Soldering Heat		Depth: completely cover the termination  Temperature (°C) Time(s) Temperature ramp/immersion and emersion rate Number of heat cycles			
		260 ±5 (solder temp) 10 ±1 25mm/s ±6 mm/s 1			



Appearance: No damage.

Impedance: within±15% of initial value
Inductance: within±10% of initial value
Q: Shall not exceed the specification value and shall not exceed the specification value e

Terminal
Strength

Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles
With the component mounted on a PCB with the device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.

DUT

wide

press tool

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.